

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

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# 60 V, 6.0 A, Low V<sub>CE(sat)</sub> PNP Transistor

ON Semiconductor's  $e^2$ PowerEdge family of low  $V_{CE(sat)}$  transistors are surface mount devices featuring ultra low saturation voltage ( $V_{CE(sat)}$ ) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC–DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e<sup>2</sup>PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

#### **Features**

- Complementary to NSS60601MZ4
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant\*

#### **MAXIMUM RATINGS** $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	-60	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	-100	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	-6.0	Vdc
Collector Current – Continuous	I <sub>C</sub>	-6.0	Α
Collector Current – Peak	I <sub>CM</sub>	-12.0	Α

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



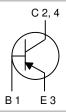
#### ON Semiconductor®

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 $\begin{array}{c} -60 \text{ VOLTS, 6.0 AMPS} \\ 2.0 \text{ WATTS} \\ \text{PNP LOW V}_{\text{CE(sat)}} \text{ TRANSISTOR} \\ \text{EQUIVALENT R}_{\text{DS(on)}} \text{ 50 m}\Omega \end{array}$ 



SOT-223 CASE 318E STYLE 1



#### **MARKING DIAGRAM**

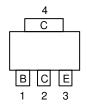


A = Assembly Location

Y = Year W = Work Week

60600 = Specific Device Code ■ Pb–Free Package

#### **PIN ASSIGNMENT**



Top View Pinout

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation $T_A = 25^{\circ}C$ Derate above 25°C	P <sub>D</sub> (Note 1)	800 6.5	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 1)	155	°C/W
Total Device Dissipation $T_A = 25^{\circ}C$ Derate above 25°C	P <sub>D</sub> (Note 2)	2 15.6	W mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 2)	64	°C/W
Total Device Dissipation (Single Pulse < 10 sec.)	P <sub>Dsingle</sub> (Note 3)	710	mW
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NSS60600MZ4T1G	SOT-223 (Pb-Free)	1,000 / Tape & Reel
NSV60600MZ4T1G	SOT-223 (Pb-Free)	1,000 / Tape & Reel
NSS60600MZ4T3G	SOT-223 (Pb-Free)	4,000 / Tape & Reel
NSV60600MZ4T3G	SOT-223 (Pb-Free)	4,000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

FR-4 @ 7.6 mm<sup>2</sup>, 1 oz. copper traces.
 FR-4 @ 645 mm<sup>2</sup>, 1 oz. copper traces.
 Thermal response.

**ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS			•	•	•
Collector – Emitter Breakdown Voltage ( $I_C = -10 \text{ mAdc}, I_B = 0$ )	V <sub>(BR)CEO</sub>	-60	_	_	Vdc
Collector – Base Breakdown Voltage ( $I_C = -0.1 \text{ mAdc}, I_E = 0$ )	V <sub>(BR)CBO</sub>	-100	-	-	Vdc
Emitter – Base Breakdown Voltage ( $I_E = -0.1 \text{ mAdc}, I_C = 0$ )	V <sub>(BR)EBO</sub>	-6.0	-	-	Vdc
Collector Cutoff Current (V <sub>CB</sub> = -100 Vdc, I <sub>E</sub> = 0)	I <sub>CBO</sub>	-	-	-0.1	μAdc
Emitter Cutoff Current (V <sub>EB</sub> = -6.0 Vdc)	I <sub>EBO</sub>	-	-	-0.1	μAdc
ON CHARACTERISTICS					
DC Current Gain (Note 4) $ \begin{aligned} &(I_C = -500 \text{ mA}, \ V_{CE} = -2.0 \text{ V}) \\ &(I_C = -1.0 \text{ A}, \ V_{CE} = -2.0 \text{ V}) \\ &(I_C = -2.0 \text{ A}, \ V_{CE} = -2.0 \text{ V}) \\ &(I_C = -6.0 \text{ A}, \ V_{CE} = -2.0 \text{ V}) \end{aligned} $	h <sub>FE</sub>	150 120 100 70	- - - -	360 - -	_
Collector – Emitter Saturation Voltage (Note 4)	V <sub>CE(sat)</sub>	- - - - -	-0.050 -0.100 -	-0.050 -0.070 -0.120 -0.250 -0.350	V
Base – Emitter Saturation Voltage (Note 4) $(I_C = -1.0 \text{ A}, I_B = -0.1 \text{ A})$	V <sub>BE(sat)</sub>	_	-	-1.0	V
Base – Emitter Turn–on Voltage (Note 4) (I <sub>C</sub> = -1.0 A, V <sub>CE</sub> = -2.0 V)	V <sub>BE(on)</sub>	-	-	-0.900	V
Cutoff Frequency ( $I_C = -500 \text{ mA}, V_{CE} = -10 \text{ V}, f = 1.0 \text{ MHz}$ )	f <sub>T</sub>	100	-	-	MHz
Input Capacitance (V <sub>EB</sub> = 5.0 V, f = 1.0 MHz)	Cibo	-	360	-	pF
Output Capacitance (V <sub>CB</sub> = 10 V, f = 1.0 MHz)	Cobo	-	60	-	pF
SWITCHING CHARACTERISTICS			•	•	•
Delay ( $V_{CC} = -30 \text{ V}$ , $I_C = 750 \text{ mA}$ , $I_{B1} = 15 \text{ mA}$ )	t <sub>d</sub>	-	100	_	ns
Rise ( $V_{CC} = -30 \text{ V}, I_C = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$ )	t <sub>r</sub>	-	180	-	ns
Storage ( $V_{CC} = -30 \text{ V}, I_C = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$ )	t <sub>s</sub>	-	540	-	ns
Fall ( $V_{CC} = -30 \text{ V}, I_C = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$ )	t <sub>f</sub>	-	145	-	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle ≤ 2%.

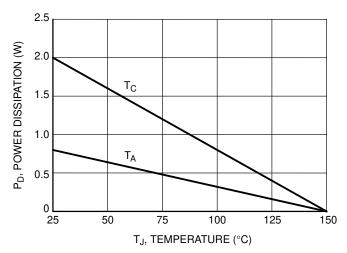


Figure 1. Power Derating

#### TYPICAL CHARACTERISTICS

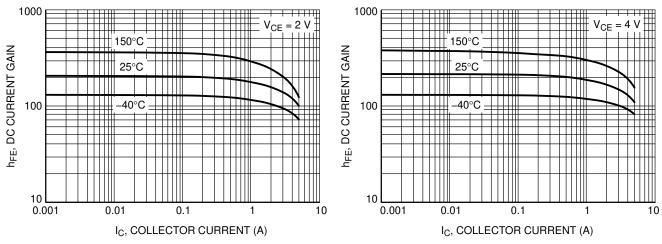


Figure 2. DC Current Gain

Figure 3. DC Current Gain

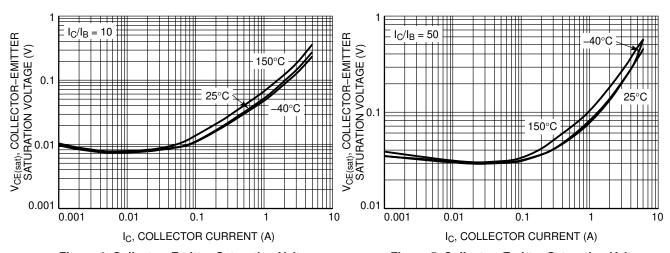


Figure 4. Collector-Emitter Saturation Voltage

Figure 5. Collector-Emitter Saturation Voltage

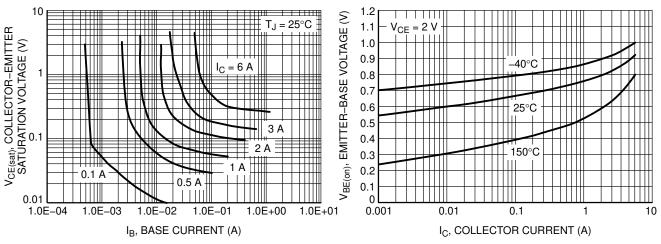
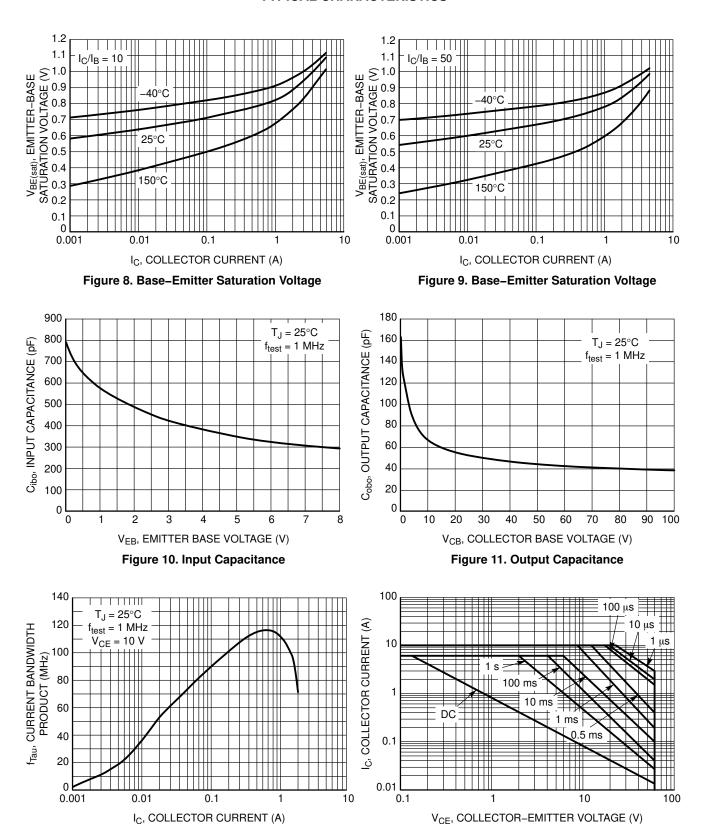


Figure 6. Collector Saturation Region

Figure 7. V<sub>BE(on)</sub> Voltage

#### TYPICAL CHARACTERISTICS



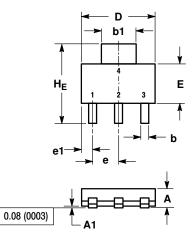
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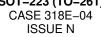
Figure 13. Safe Operating Area

Figure 12. Current-Gain Bandwidth Product

#### PACKAGE DIMENSIONS

#### SOT-223 (TO-261) CASE 318E-04



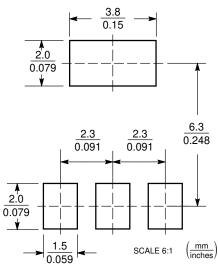


- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.50	1.63	1.75	0.060	0.064	0.068
A1	0.02	0.06	0.10	0.001	0.002	0.004
b	0.60	0.75	0.89	0.024	0.030	0.035
b1	2.90	3.06	3.20	0.115	0.121	0.126
n	0.24	0.29	0.35	0.009	0.012	0.014
D	6.30	6.50	6.70	0.249	0.256	0.263
Е	3.30	3.50	3.70	0.130	0.138	0.145
е	2.20	2.30	2.40	0.087	0.091	0.094
e1	0.85	0.94	1.05	0.033	0.037	0.041
Г	0.20			0.008		
L1	1.50	1.75	2.00	0.060	0.069	0.078
HE	6.70	7.00	7.30	0.264	0.276	0.287
θ	0°	_	10°	0°	-	10°

STYLE 1: PIN 1.

- COLLECTOR EMITTER
- COLLECTOR
- **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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